

**PRODUCTION OF COPPER ALLOY HAVING EXCELLENT PEELING  
RESISTANCE OF TIN OR TIN ALLOY PLATING**

Patent Number: JP63262448  
Publication date: 1988-10-28  
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Requested Patent: ☐ JP63262448  
Application Number: JP19870096217 19870421  
Priority Number(s):  
IPC Classification: C22F1/08 ; C22C9/06  
EC Classification:  
Equivalents: JP8000957B

**Abstract**

**PURPOSE:** To improve the thermal peeling resistance of tin (alloy) plating and to provide good strength, spring characteristics, heat resistance and electroconductivity together to the titled copper alloy by specifying the aging treatmental conditions of the copper alloy contg. specific ratios of Ni and Si.  
**CONSTITUTION:** The copper alloy contg. by weight, 0.4-4.0% Ni, 0.1-1.0% Si and the balance consisting of copper with inevitable impurities is subjected to the aging treatment at T deg.C. At this time, aging treatment is executed for longer times than the times at which the hardness H (Hv) expressed by the equation can be obtd. The copper alloy subjected to the above-mentioned aging treatment is preferably cold rolled as well at about  $\geq 5\%$  working ratio and is annealed at about 350-800 deg.C if necessary. The total 0.001-3.0% of one or more kinds among Zn, P, Sn, As, Cr, Mg, Mn, Sb, Fe, Co, Al, Ti, Zr, Be, Ag, Pb, B, Hf, In and lanthanoids are furthermore added as the secondary component to said alloy at need.

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